

## Broadband powerline communication SoC optimized for audio/video streaming and consumer applications

Datasheet - production data



- Master/slave SSI
- Two independent UARTs
- Fast IrDA®
- Real-time clock
- Configurable serial port (SPORT) interface for external DSP and audio codec (ADC and DAC) in I<sup>2</sup>S mode
- Transport stream interface (video TS)
- Vectored interrupt controller (VIC)
- JTAG (IEEE1149.1) interface
- Three CPU instruction sets

### Features

- Configurable HW engine for multiple HomePlug® PHY and real-time MAC layers processing supporting:
  - HomePlug AV and 1.0 standards
  - HomePlug Green PHY™ standard
- Integrated analog front-end
- ARM926EJ-S™ 32-bit RISC CPU up to 333 MHz
- 8/16 bit DDR mobile at 166 MHz and DDR2 at 333 MHz memory controller
- Serial memory interface
- 8/16-bits NOR Flash/NAND Flash and SRAM memories controllers
- Multichannel DMA controller
- Ethernet 10/100 MAC with MII interface
- USB 2.0
- PCI Express and S-ATA
- Color LCD (CLCD) controller
- JPEG codec accelerator
- Cryptographic coprocessor
- Up to 40 GPIOs
- Enhanced I<sup>2</sup>S (digital audio interface)
- I<sup>2</sup>C master/slave mode

### Applications

The SStreamPlug ST2100 is configurable for a wide range of consumer and industrial<sup>(a)</sup> powerline applications such as:

- Smart gateway
- Powerline communication bridging, including wireless
- Smart grid
- Electric vehicle charging station<sup>(a)</sup>
- In house audio/video distribution
- Video surveillance
- Home automation
- “Network Area Storage” (NAS)
- Display panels control

Table 1. Device summary

Order code	Operating temp. range	Package	Packing
ST2100	-40 to +85 °C	TFBGA 12 x 12 x 1.2 mm, pitch 0.5 mm	Tray, tape and reel

a. Not intended for automotive usage .

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# 1 Description

The SStreamPlug ST2100 device is the STMicroelectronics® “Broad Band Powerline Communication” (BB PLC) solution, based on the powerful ARM926EJ-S™ processor (up to 333 MHz), widely used in applications where high computation performance is required, such as consumer (“Home Area Network” or HAN), industrial and smart grid applications.

In addition, the SStreamPlug ST2100 has a memory management unit (MMU) that allows virtual memory management - making the system compliant with the Linux® operating system. It also offers 16 Kbyte of data cache, 32 Kbyte of instruction cache, JTAG and ETM™ (Embedded Trace Macrocell™ ) for debug operations.

A large set of peripherals allows a wide flexibility of the usage of the system in most of the possible PLC broadband applications (indoor and outdoor).

## 2 Main features

- Configurable hardware engine for multiple HomePlug PHY and real-time MAC layers
  - HomePlug™ AV and 1.0 standards
  - HomePlug Green PHY standard
- Integrated analog front-end
  - Programmable gain amplifier: gain range -12 dB to 48 dB
  - ADC and DAC
  - 2.5 V voltage regulator
  - Zero crossing (ZC) comparator
- ARM926EJ-S™ 32-bit RISC CPU up to 333 MHz
  - 16 Kbyte if instruction cache, 16 Kbyte of data cache
  - 32 Kbyte of instruction TCM and 16 Kbyte of data TCM
  - Three instruction sets: 32-bit for high performance, 16-bit (Thumb®) for efficient code density, bytecode Java™ mode (Jazelle™) for direct execution of Java code
  - AMBA™ bus interface with  $f_{MAX}$  166 MHz
- 48 Kbyte on-chip boot ROM
- 8 Kbyte on-chip SRAM
- 8/16 bit DDR mobile at 166 MHz and DDR2 at 333 MHz memory controller
- Serial memory interface
- 8/16-bits NOR Flash/NAND Flash and SRAM memory controller
- Boot capability from NAND Flash, serial/parallel NOR Flash, and UART
- Multichannel DMA controller (8 FIFOs and 16 dedicated channels)
- Ethernet 10/100 MAC with MII interface (IEEE 802.3), RevMII, IEEE 802.1-AS and 802.1-Qav for audio video (AV) traffic
- USB 2.0 (high-full-low speed) port with an integrated PHY able to work as a host or device
- PCI Express GEN1 (PCI Express standard version 1.1), single lane X1 dual mode (both “Root Complex” and “Endpoint” modes supported), the PHY is a standard 8-bit/16-bit PIPE PHY interface. This peripheral supports also the serial ATA compliant with the SATA/150.
- Color LCD controller (up to 1024 x 768 resolution at 24 bpp true color, STN/TFT display panels)
- JPEG codec accelerator (1 clock/pixel)
- Cryptographic coprocessor (DMA based programmable engine) with support for:
  - Advanced encryption standard (AES) cipher (128, 192, 256 bit keys) in ECB, CBC, CTR modes
  - Data encryption standard (DES) and triple DES (TDES) cipher in ECB and CBC modes
  - SHA-1, HMAC-SHA-1, SHA-256, HMAC-SHA-256, MD5, HMAC-MD5 digests
- Up to 40 GPIOs (multiplexed with peripheral I/Os), all the I/Os have interrupt capability, 24 application specific GPIOs: four I/Os support PWM and four I/Os support double PWM features.

- Enhanced I<sup>2</sup>S for 4-channel “Digital Audio Interface” (DAI)
- Master/slave SSP (Motorola SPI, Texas Instruments, National Semiconductor protocols) up to 5 Mbits/s in slave mode and up to 20 Mbits/s in master mode
- I<sup>2</sup>C master/slave mode
- Two independent UARTs supporting hardware (HW) flow control
- Fast IrDA (SIR/MIR/FIR)
- Three pairs of 16-bit general purpose timers with programmable 8-bit prescaler
- Real-time clock (RTC)
- Configurable serial port (SPORT) interface for external DSP and audio codec (ADC and DAC in I<sup>2</sup>S mode)
- Transport stream interface (Video TS also called “Synchronous peripheral bus”) for external MPEG- 2/H.264 encoder and decoder. TS port also implements image sensor interface (CCD camera)
- Watchdog timer
- Clock synthesizer (4 outputs)
- Vectored interrupt controller (VIC)
- JTAG (IEEE1149.1) interface
- ETM9 interface
- Multichannel cryptographic coprocessor. DES/TDES and AES security for the powerline link
- PGC (IR) interface
- Supply voltages: 1.2 V core, 1.8 V / 2.5 V DDR, 2.5 V AFE and PLLs, 1.5 V RTC and 3.3 V I/Os
- Available in a TFBGA373 package (12 x 12 x 1.2 mm, pitch 0.5 mm).



### 3 Architecture description

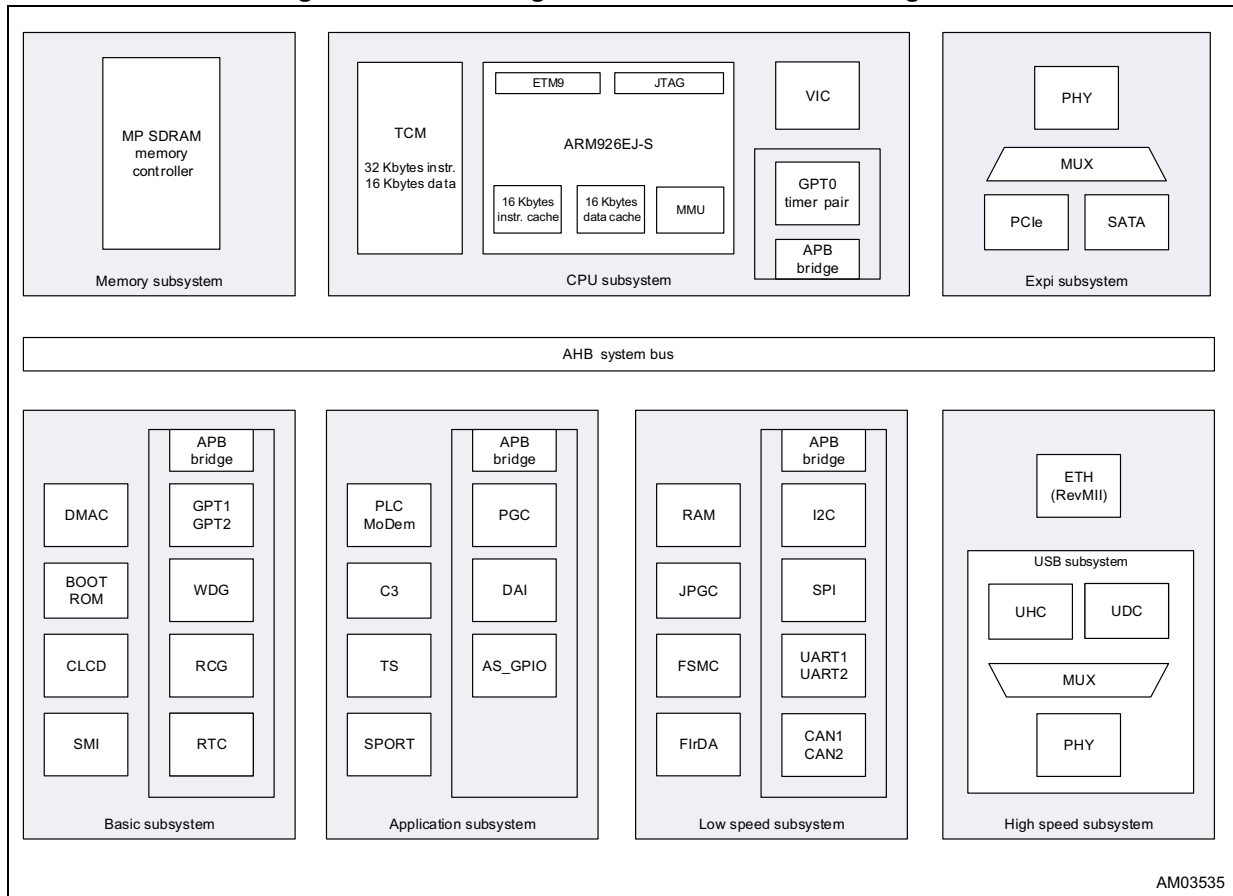
Figure 1 is the architecture overview of the SStreamPlug ST2100.

The internal architecture is based on several shared subsystems interconnected through a multilayer system bus.

The bus structure allows different subsystem data flows to be executed in parallel improving the core platform efficiency.

High performance master agents are directly interconnected with the memory controller reducing the memory access latency.

Figure 1. SStreamPlug ST2100 functional block diagram



### 3.1 CPU subsystem

- ARM926EJ-S™ running at 333 MHz with:
  - MMU
  - 16 Kbyte of instruction cache
  - 16 Kbyte of data cache
  - 32 Kbyte of instruction “Tightly Coupled Memory” (TCM)
  - 16 Kbyte of data “Tightly Coupled Memory” (TCM)
  - AMBA bus interface
  - JTAG
  - ETM9 (Embedded Trace Macrocell) for debug, medium size version
- Interrupt controller managing sources which are prioritized and vectorized

### 3.2 System bus

The system bus structure allows different subsystem data flows to be executed in parallel improving the core platform efficiency.

High performance master agents are directly interconnected with the memory controller reducing the memory access latency. The overall memory bandwidth assigned to each master port can be programmed and optimized through an internal efficient weighted round-robin arbitration mechanism.

Table 2 shows the system bus scheme and Table 3 is the key to its contents.

**Table 2. System bus connectivity**

		CPU	PCIe/SATA	DMA 1	DMA 2	Eth.	TS/SPORT	UHC/JDC	PLC modem	Crypto	CLCD
<b>Targets (slave ports)</b>	MP SDRAM	X	X	X	X	X	X	X	X	X	X
	Low speed	X	X	X							
	Application	X	X		X						
	Basic	X	X								
	High speed	X	X								
	Expi	X			X						

**Table 3. Key to system bus connectivity matrix**

Format	Definition
Grey box	No connection exists between target and initiator
X	A connection exists between target and initiator

### 3.3 Memory subsystem

The multiport memory controller within the memory subsystem manages DDR mobile up to 166 MHz and DDR2 up to 333 MHz external memory. Internally, it handles 5 ports supporting all the chip master ports.

The multiport memory controller block has a programmable arbitration scheme and the transactions happen on a different layer from the main bus. It also offers a local FIFO to increase the throughput and reduce the latency.

### 3.4 Expi subsystem

- PCI Express Gen1 (PCI Express standard version 1.1) single lane X1 dual mode
  - Root Complex mode is supported.
  - Endpoint mode is supported.
- Serial ATA compliant with SATA/150 specifications
- PHY is standard 8-bit/16-bit PIPE PHY interface

### 3.5 Basic subsystem

- 8 FIFOs and 16 high performance DMA channels with two AHB interfaces to parallelize the activity when two channels are working at the same time.
- 48 Kbytes of ROM (for boot procedure)
- “Serial Memory Interface” (SMI) supporting external serial Flash.
- Color LCD controller (CLCD) up to 1024 x 768 resolution at 24 bpp (true color) supporting STN/TFT display panels
- Three pair of 16 bit general purpose timers with programmable prescaler
- Watchdog timer
- RTC with separate power supply allowing battery connection
- Up to 104 “Multi-Function” I/Os (MFIOs) multiplexed with peripheral I/Os:
  - Allows a large number of possible application scenarios
  - Up to 40 GPIOs with interrupt capability
- System controller, reset and clock generation, and miscellaneous registers array allowing a full configurability of the system.

### 3.6 High-speed connectivity subsystem

- Ethernet 10/100 MAC with MII interface (IEEE 802.3), with external PHY
  - RevMII (supporting 25 and 50 MHz clock frequencies)
  - IEEE 802.1-AS and 802.1-Qav for audio video (AV) traffic
- USB 2.0 (high-full-low speed) port with integrated PHY able to work as a host or device. The PHY is embedded.
  - One USB host controller compatible with USB 2.0 high-speed specification managing a single port. The peripheral has a dedicated channel to the multiport memory controller and a dedicated slave port for CPU programming (OHCI and EHCI).
  - One USB device compatible with USB 2.0 high-speed specifications. A dedicated channel connects the peripheral with the multiport memory controller and registers and an internal FIFO are accessible from the CPU through the main AHB bus. A USB plug detector block is also available to detect the presence of the VBUS voltage.

### 3.7 Low-speed connectivity subsystem

- Two independent UARTs supporting hardware flow control up to 460.8 Kbits/s
- Fast IrDA controller with a speed rate from 9.6 Kbits/s to 4 Mbits/s (SIR/MIR/FIR)
- One synchronous “Serial Port Interface” (SPI) controller capable of operating as a master or a slave (Motorola - Texas Instruments - National Semiconductor) with a speed (data) rate up to 20 Mbits/s
- One I<sup>2</sup>C (also known as a digital audio interface) controller capable of operating in master and slave mode and covering all the possible data rates (high, fast and low)
- JPEG codec accelerator (1 clock per pixel)
- 8 Kbytes of static RAM
- “Flexible Static Memory Controller” (FSMC) supporting:
  - Asynchronous parallel NAND and NOR Flash memories
  - Synchronous and asynchronous SRAM
- Two independent “Controller Area Network” (CAN) interfaces compliant with CAN protocol version 2.0 parts A and B (up to 1 Mbit/s).

### 3.8 Application subsystem

- Configurable hardware engine for multiple HomePlug PHY and real-time MAC layers processing supporting:
  - HomePlug AV and 1.0 standards
  - HomePlug Green PHY standard
- Integrated analog front-end:
  - Programmable gain amplifier: gain range -12 dB to 48 dB
  - ADC and DAC
  - 2.5 V, 150 mA voltage regulator
  - Zero crossing (ZC) comparator
- Cryptographic coprocessor channels (C3), DMA based programmable engine, with support for:
  - Advanced encryption standard (AES) cipher (128-, 192-, 256-bit keys) in ECB, CBC, CTR modes
  - Data encryption standard (DES) and triple DES cipher in ECB and CBC modes
  - SHA-1, HMAC-SHA-1, SHA-256, HMAC-SHA-256, MD5, HMAC-MD5 digests algorithms
- Configurable serial port (SPORT) interface for external DSP and audio codec (ADC and DAC in I<sup>2</sup>S mode)
- Transport stream (TS) interface
- Pulse generator and capture (PGC) (IR) for remote controls
- 4-channel I<sup>2</sup>S [“Digital Audio Interface” (DAI)]
- 24 application specific GPIOs:
  - Up to 4 GPIOs supporting PWM
  - Up to 4 GPIOs supporting double PWM.

### 3.9 Clock and reset system

- The system clocks are generated by:
  - Two fully programmable PLLs. One is used to generate a clock for CPU and AMBA AHB bus and the other is used in case the DDR clock has to be different (asynchronous) with respect to the CPU clock.
  - One “high precision” clock synthesizer with 4 outputs providing different frequencies for the various IPs
- Fully programmable control of the clock and reset signals for all the slave blocks allowing sophisticated power management.

## 4 Pin descriptions

From [Table 4](#) to [Table 15 on page 21](#) and [Table 16](#) in [Section 5 on page 30](#) describe the SStreamPlug ST2100 pinouts.

### 4.1 Dedicated pins

**Table 4. Master clock RTC, RESET and 3.3 V comparator pin descriptions**

Group	Signal name	Ball	Direction	Function	Pin type
Master clock	RCG_MCLK_A	AB18	In	24 MHz (typical) crystal in	Oscillator 2.5 V capable
	RCG_MCLK_ZO	AB19	Out	24 MHz (typical) crystal out	Oscillator 2.5 V capable
RTC	RTC_TST	G23	In	POR test signal	Keep it at GND
	RTC_ZO	H22	Out	32 KHz crystal output	Oscillator 1.5 V capable
	RTC_A	H23	In	32 KHz crystal input	Oscillator 1.5 V capable
	RTC_SGN	J23	In	POR signal	Keep it floating
RESET	MRESET	Y13	In	Main reset	TTL Schmitt trigger input buffer 3.3 V tolerant with PU
3.3 V comp.	COMP_3V3_ANAREXT	A21	Power	External resistor for 3.3 V I/Os compensation	Analog, 3.3 V capable
	COMP_3V3_GNDBGCOMP	A22	Power	Return for external resistor for 3.3 V I/Os compensation	-

**Table 5. Power supply pin descriptions**

Group	Signal name	Ball	Value
DIGITAL GROUND	GND	A1, A23, D5, D20, J11, J13, K10,K11, K12, K13, K14,K22, L10, L11, L12, L13, L14, L21, M1, M4, M10, M11, M12, M13, M14, M20, N10, N11, N12, N13, N14, P10, P11, P12, P13, P14, R11, R13, R22, AC1, AC23, AB23	0 V
	DVSS_USB	AB17	
	GND_ADC	V21	
	GND_DAC	T23	
	GND_RCG_CLK_SYNTH	AA19	

Table 5. Power supply pin descriptions (continued)

Group	Signal name	Ball	Value
ANALOG GROUND	GNDE_RTC	J22	0 V
	VSSA_USB	AC16	-
	VSSA_USB	AC13	-
	VSSAC_USB	AA15	-
	GNDAS_ADC	W21	-
	GND_A_ADC	W22	-
	GND_A1_DAC	V20	-
	GND_A2_DAC	T22	-
	GNDAS_DAC	U20	-
	DAC_MASS_QUIET	U22	-
	GNDE_DAC	W20	-
	GNDE_RCG_MCLK	AC19	-
	AGNDSUB_RCG_MCLK	Y17	-
	AGND_RCG_MCLK	AA17	-
	AGND_PLL1	Y15	-
	AGND_PLL2	W17	-
	GND_A_RCG_CLK_SYNTH	Y20	-
	GNDE_REG	AB22	-
	GNDE_PGA	AB21	-
	PCIE_P1_VSSR	K23	-
	PCIE_P1_VSSR	M23	-
	PCIE_P1_VSST	N23	-
PCIE_VSS_PLL	P21	-	
PCIE_P1_VSST	R23	-	
I/O	VDDE_3V3	E5, E6, E7, E17, E18, E19, F5, F19, G5, G19, U5, U19, V5, V19, W5, W6, W7, W18, W19	3.3 V
CORE	VDD_1V2	J9, J10, J12, J14, J15, K9, K15, L9, L15, M9, M15, N9, N15, P9, P15, R9, R10, R12, R14, R15, AA21	1.2 V
USB PHY	VDD_1V2_USB	AB15	1.2 V
	VDD_2V5_USB	AA16	2.5 V
	VDD_3V3_USB	AB16	3.3 V

Table 5. Power supply pin descriptions (continued)

Group	Signal name	Ball	Value
PCIe PHY	PCIe_VDD_PLL	M21	1.2 V
	PCIe_P1_VDDR	M22	1.2 V
	PCIe_P1_VDDT1	N21	1.2 V
	PCIe_P1_VDDT2	N22	2.5 V
	PCIe_VDD2_PLL	R21	2.5 V
OSCI (master clock)	VDD_1V2_RCG_MCLK	AA18	1.2 V
	VDDE_2V5_RCG_MCLK	AC18	2.5 V
PLL 1	AVDD_2V5_PLL1	Y16	2.5 V
PLL 2	AVDD_2V5_PLL2	Y14	2.5 V
SYNTH	VDD_1V2_RCG_CLK_SYNTH	Y19	1.2 V
	VCCA_2V5_RCG_CLK_SYNTH	Y18	2.5 V
DDR	VDDE_DDR	A5, A11, A14, A20, C23, D6, D11, D14	1.8 V / 2.5 V
AFE_ADC	VDD_1V2_ADC	W23	1.2 V
	VCCAISO_2V5_ADC	Y21	2.5 V
	VCCA_2V5_ADC	Y23	2.5 V
AFE_DAC	VDD_1V2_DAC	T21	1.2 V
	VCCA1_2V5_DAC	U21	2.5 V
	VCCA2_2V5_DAC	T20	2.5 V
AFE_PGA	VDD_2V5_PGA	AB20	2.5 V
	VDDE_3V3_PGA	AC20	3.3 V
OSCI RTC	VDD_1V5_RTC	G22	1.5 V
Internal 2.5 V regulator	VDDE_2V5_REG (REG OUT)	Y22	2.5 V
	VDDE_3V3_REG (REG IN)	AA22	3.3 V
Reserved	Reserved	AA23, B23, D21, D22, D23, E20, E21, E22, E23, F20, F21, F22, F23, G20, G21, H20, H21, J20, J21, K20, K21, L20	Keep it floating
Reserved	Reserved	B22	Connect to GND



Table 6. Debug pin descriptions

Signal name	Ball	Direction	Function	Pin type
Reserved	B4	In	Reserved Connect to GND	TTL input buffer, 3.3 V tolerant with PD
JTAG_TMS	C5	In	Test mode select	TTL input buffer, 3.3 V tolerant with PU
JTAG_TCK	D4	In	Test clock	TTL input buffer, 3.3 V tolerant with PU
JTAG_NTRST	E4	In	Test reset input	TTL input buffer, 3.3 V tolerant with PU
JTAG_TDI	F4	In	Test data input	TTL input buffer, 3.3 V tolerant with PU
JTAG_TDO	G4	Out	Test data output	TTL output buffer, 3.3 V capable, 4 mA
ETM_TRACECLK	Y7	Out	ETM clock (the other ETM signals are available on MFIOs)	TTL output buffer, 3.3 V capable, 4 mA

Table 7. Boot source descriptions

Signal name	Ball	Direction	Function	Pin type
SOC_CFG_BOOT0	C2	In	Boot mode configuration	TTL input buffer, 3.3 V tolerant with PD
SOC_CFG_BOOT1	B2	In	Boot mode configuration	TTL input buffer, 3.3 V tolerant with PD
SOC_CFG_BOOT2	C3	In	Boot mode configuration	TTL input buffer, 3.3 V tolerant with PD
SOC_CFG_BOOT3	B3	In	Boot mode configuration	TTL input buffer, 3.3 V tolerant with PD

**Table 8. Boot source selection**

Boot source	SOC_CFG_BOOT3	SOC_CFG_BOOT2	SOC_CFG_BOOT1	SOC_CFG_BOOT0
SMI (3-byte addressing)	0	0	0	0
SMI (2-byte addressing)	0	0	0	1
FSMC/NAND 8-bit	0	0	1	0
FSMC/NAND 16-bit	0	0	1	1
UART1 (G20)	0	1	0	0
UART2(G21)	0	1	0	1
FSMC/NOR 8-bit	0	1	1	0
FSMC/NOR 16-bit	0	1	1	1
Reserved	1	X <sup>(1)</sup>	X <sup>(1)</sup>	X <sup>(1)</sup>

1. An "X" may be a "1" or a "0".

**Table 9. SMI pin descriptions**

Signal name	Ball	Direction	Function	Pin type
SMI_DIN	A2	In	Serial Flash input data	TTL input buffer, 3.3 V tolerant with configurable PU/PD and HYST
SMI_DOUT	A3	Out	Serial Flash output data	TTL output buffer, 3.3 V capable, 4 mA
SMI_CLK	A4	I/O	Serial Flash clock	TTL output buffer, 3.3 V capable, 4 mA
SMI_NCS0	B1	Out	Serial Flash chip select	TTL output buffer, 3.3 V capable, 4 mA
SMI_NCS1	C1	Out	Serial Flash chip select	TTL output buffer, 3.3 V capable, 4 mA
SMI_NCS2	D1	Out	Serial Flash chip select	TTL output buffer, 3.3 V capable, 4 mA

**Table 10. USB Pin descriptions**

Signal name	Ball	Direction	Function	Pin type
USB_VBUS	AA14	I/O	USB device VBUS detect or USB host VBUS control	Bidirectional TTL pad, 3.3 V tolerant input with PD for device mode; output for host mode
USB_OVERCUR	AB13	In	USB host overcurrent	TTL input buffer 3.3 V tolerant with PU (for host mode only)
USB_TXRTUNE	AB14	Out	Reference resistor	Analog
USB_DP	AC14	I/O	USB host or device D+	Bidirectional analog buffer 5 V tolerant
USB_DM	AC15		USB host or device D-	Bidirectional analog buffer 5 V tolerant
Reserved	AC17	Out	Do not connect test output	Analog

Table 11. PCIe / SATA pin descriptions

Signal name	Ball	Direction	Function	Pin type
PCIE_P1_RXN	L22	In	High frequency negative RX input signal	Analog
PCIE_P1_RXP	L23	In	High frequency positive RX input signal	Analog
PCIE_XTAL2	N20	Out	Feedback of the crystal oscillator	Oscillator
PCIE_XTAL1	P20	In	Input of the crystal oscillator	Oscillator
PCIE_P1_TXP	P22	Out	High frequency positive TX output signal	Analog
PCIE_P1_TXN	P23	Out	High frequency negative TX output signal	Analog
PCIE_REFRES	R20	Input	Reference resistor for the impedance compensation	Analog

Table 12. Internal AFE pin descriptions

Signal name	Ball	Direction	Function	Pin type
DAC_IDAC	U23	Out	HF DAC differential positive current "Out"	Analog
DAC_REXT	V22	Out	External precision resistor	Analog
DAC_IDACB	V23	Out	HF DAC differential negative current "Out"	Analog
PGA_IN_N	AC21	In	PGA negative input	Analog
PGA_IN_P	AC22	In	PGA positive input	Analog

Table 13. AC crossing pin descriptions

Signal name	Ball	Direction	Function	Pin type
AC_CROSSING	C4	In	Mains digital input, zero crossing	TTL input buffer, 3.3 V tolerant, with configurable PU/PD and HYST
ZC_IN	AA20	In	Mains analog zero crossing	Analog

Table 14. External PLI pin description

Signal name	Ball	Direction	Function	Pin type
EXTPLI_TXON	C22	Out	Line driver enable	TTL output buffer, 3.3 V capable, 4 mA

Table 15. DDR pin descriptions

Signal name	Ball	Direction	Function	Pin type
DDR_ADDR_0	D7	Out	Address lines	Compatible with DDRI (SSTL2) and DDRII (SSTL18)
DDR_ADDR_1	C7			
DDR_ADDR_2	B7			
DDR_ADDR_3	A8			
DDR_ADDR_4	B8			
DDR_ADDR_5	C8			
DDR_ADDR_6	D8			
DDR_ADDR_7	A9			
DDR_ADDR_8	B9			
DDR_ADDR_9	C9			
DDR_ADDR_10	D9			
DDR_ADDR_11	A10			
DDR_ADDR_12	B10			
DDR_ADDR_13	C10			
DDR_ADDR_14	D10			
DDR_BA_0	C11	Out	Bank select	Differential Compatible with DDRI (SSTL2) and DDRII (SSTL18)
DDR_BA_1	D12			
DDR_BA_2	C12			
DDR_RAS	B14	Out	Row address strobe	
DDR_CAS	B13	Out	Column address strobe	
DDR_WE	B11	Out	Write enable	
DDR_CLKEN	B12	Out	Clock enable	
DDR_CLK_P	A12	Out	Differential clock	
DDR_CLK_N	A13			

Table 15. DDR pin descriptions (continued)

Signal name	Ball	Direction	Function	Pin type
DDR_CS_0	C13	Out	Chip select	Compatible with DDRI (SSTL2) and DDRII (SSTL18)
DDR_CS_1	C14			
DDR_ODT_1	A6	I/O	On-die termination enable lines	
DDR_ODT_0	A7			
DDR_DATA_0	D15	I/O	Data lines (lower byte)	
DDR_DATA_1	C15			
DDR_DATA_2	D16			
DDR_DATA_3	C16			
DDR_DATA_4	C18			
DDR_DATA_5	D18			
DDR_DATA_6	C17			
DDR_DATA_7	D17			
DDR_DQS_0	A15	Out	Lower data strobe	Differential Compatible with DDRI (SSTL2) and DDRII (SSTL18)
DDR_NDQS_0	A16			
DDR_DM_0	B15	Out	Lower data mask	Compatible with DDRI (SSTL2) and DDRII (SSTL18)
DDR_GATE_0	A17	I/O	Lower gate open	
DDR_DATA_8	C21	I/O	Data lines (upper byte)	
DDR_DATA_9	B21			
DDR_DATA_10	C20			
DDR_DATA_11	B20			
DDR_DATA_12	D19			
DDR_DATA_13	C19			
DDR_DATA_14	B19			
DDR_DATA_15	B18			
DDR_DQS_1	A18	Out	Upper data strobe	Differential Compatible with DDRI (SSTL2) and DDRII (SSTL18)
DDR_NDQS_1	A19			
DDR_DM_1	B16	Out	Upper data mask	Compatible with DDRI (SSTL2) and DDRII (SSTL18)
DDR_GATE_1	B17	I/O	Upper gate open	
VREF_DDR	D13	In	Reference voltage	Analog 1.8 V
DDR2_EN	B5	In	Configuration	TTL input buffer, 3.3 V tolerant, with PU
COMP_1V8_ANAREXT	B6	Power	External resistor for 1.8 V I/Os compensation	Analog 1.8 V capable
COMP_1V8_GNDBGCOMP	C6	Power	Return for external resistor for 1.8 V I/Os compensation	Power

## 4.2 Shared I/O pins (MFIOs)

The 104 MFIOs can be configured in different modes. This allows the SStreamPlug ST2100 to be tailored for various applications.

For the MFIO from 88 to 103, the signal specified in [Table 16](#) is also conditioned by an internal selection MUX that can choose among the specified signal and an internal basic subsystem general purpose IO (BS\_GPIO), as specified in the SStreamPlug ST2100 manual and shown in [Figure 2](#) and [Figure 3](#).

Figure 2. MIFO 0-87 muxing scheme

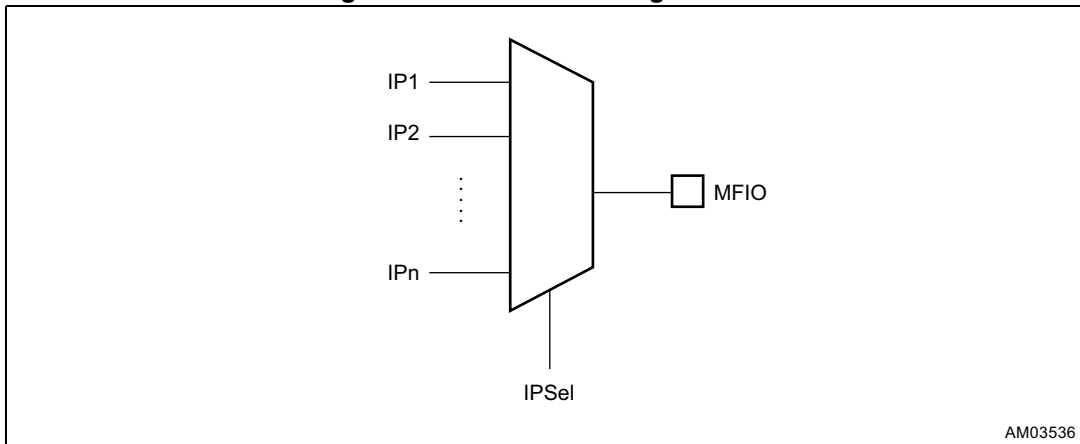
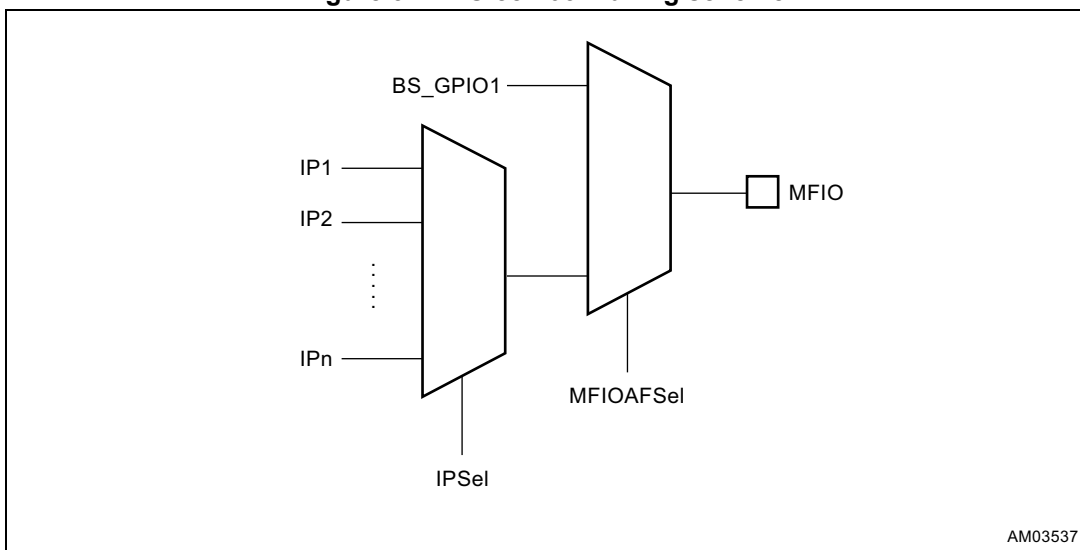


Figure 3. MIFO 88-103 muxing scheme



**Table 16. MFIO pin descriptions**

Ball no.	Signal name	Muxing selection					
		0	1	2	3	4	5
AB9	MFIO0	eth_phy_int	FSMC_BLn0	FSMC_PCSel0	-	-	ETM_TRACEPKTA_0
AA8	MFIO1	eth_clk	FSMC_BLn1	FSMC_PCSel1	-	-	ETM_TRACEPKTA_1
AB6	MFIO2	MII_TXER	FSMC_PCOEn	FSMC_PCOEn	-	-	ETM_TRACEPKTA_2
AA7	MFIO3	MII_TXEN	FSMC_PCWEn	FSMC_PCWEn	-	-	ETM_TRACEPKTA_3
AA9	MFIO4	MII_TXD_3	FSMC_Ebar0	FSMC_PCIntRq_1	-	-	ETM_TRACEPKTB_0
AB7	MFIO5	MII_TXD_2	FSMC_Ebar1	FSMC_PCIntRq_2	-	-	ETM_TRACEPKTB_1
AA6	MFIO6	MII_TXD_1	FSMC_Ebar2	FSMC_PCAD16(CLE)	-	-	ETM_TRACEPKTB_2
AB8	MFIO7	MII_TXD_0	FSMC_Ebar3	FSMC_PCAD17(ALE)	-	-	ETM_TRACEPKTB_3
AB5	MFIO8	MII_TXCLK	FSMC_PCDa0	-	-	-	ETM_TRACE_SYNCA
AC8	MFIO9	MII_RXER	FSMC_PCDa1	-	-	-	ETM_PIPESTATA_0
AC5	MFIO10	MII_RXDV	FSMC_PCDa2	-	-	-	ETM_PIPESTATA_1
AC7	MFIO11	MII_RXD_3	FSMC_PCDa3	-	-	-	ETM_PIPESTATA_2
AB4	MFIO12	MII_RXD_2	FSMC_PCDa4	-	-	-	ETM_TRACE_SYNCB
AC6	MFIO13	MII_RXD_1	FSMC_PCDa5	-	-	-	ETM_PIPESTATB_0
AA5	MFIO14	MII_RXD_0	FSMC_PCDa6	-	-	-	ETM_PIPESTATB_1
AC4	MFIO15	MII_RXCLK	FSMC_PCDa7	-	-	-	ETM_PIPESTATB_2
AA4	MFIO16	MII_MDIO	FSMC_PCAD0	-	-	-	AS_GPIO8
AC3	MFIO17	MII_MDC	FSMC_PCAD1	-	-	-	AS_GPIO9
AB3	MFIO18	MII_CRS	FSMC_PCAD2	-	-	-	AS_GPIO10
AC2	MFIO19	MII_COL	FSMC_PCAD3	-	-	-	AS_GPIO11
Y3	MFIO20	UART2_CTS	FSMC_PCAD4	-	-	-	AS_GPIO12
AB2	MFIO21	UART2_RTS	FSMC_PCAD5	-	-	-	AS_GPIO13



Table 16. MFIO pin descriptions (continued)

Ball no.	Signal name	Muxing selection					
		0	1	2	3	4	5
Y4MFIO22	UART2_RXD	FSMC_PCAD6	-	-	-	AS_GPIO14	-
AA3	MFIO23	UART2_TXD	FSMC_PCAD7	-	-	-	AS_GPIO15
Y5	MFIO24	UART1_CTS	FSMC_PCDa8	-	-	-	-
AA1	MFIO25	UART1_RTS	FSMC_PCDa9	-	-	-	-
Y6	MFIO26	UART1_RXD	FSMC_PCDa10	-	-	-	-
AB1	MFIO27	UART1_TXD	FSMC_PCDa11	-	-	-	-
W4	MFIO28	AS_GPIO4	FSMC_PCDa12	-	-	-	-
Y1	MFIO29	AS_GPIO5	FSMC_PCDa13	-	-	-	-
V3	MFIO30	AS_GPIO6	FSMC_PCDa14	-	-	-	-
V2	MFIO31	AS_GPIO7	FSMC_PCDa15	-	-	-	-
W3	MFIO32	AS_GPIO0	FSMC_PCAD8	-	-	-	-
Y2	MFIO33	AS_GPIO1	FSMC_PCAD9	-	-	-	-
U3	MFIO34	AS_GPIO2	FSMC_PCAD10	-	-	-	-
W2	MFIO35	AS_GPIO3	FSMC_PCAD11	-	-	-	-
V4	MFIO36	AS_GPIO8	FSMC_PCAD12	-	-	-	-
AA2	MFIO37	AS_GPIO9	FSMC_PCAD13	-	-	-	-
U2	MFIO38	AS_GPIO10	FSMC_PCAD14	-	-	-	-
W1	MFIO39	AS_GPIO11	FSMC_PCAD15	-	-	-	-
U4	MFIO40	AS_GPIO12	-	-	-	FSMC_PCAD16	-
V1	MFIO41	AS_GPIO13	-	-	-	FSMC_PCAD17	-
T3	MFIO42	AS_GPIO14	PGC_IR_TX	FirDA_RX	-	FSMC_PCAD18	-
T1	MFIO43	AS_GPIO15	PGC_IR_RX	FirDA_TX	-	FSMC_PCAD19	-
R4	MFIO44	SPORT_DRSEC2	-	-	RxQuiet	FSMC_PCAD20	-



**Table 16. MFIO pin descriptions (continued)**

Ball no.	Signal name	Muxing selection					
		0	1	2	3	4	5
U1	MFIO45	SPORT_DRSEC1	TS_DATA7	-	XGAIN	FSMC_PCAD21	-
R3	MFIO46	SPORT_DRSEC0	TS_DATA6	-	TX_EN2	FSMC_PCAD22	-
R2	MFIO47	SPORT_DTSEC2	TS_DATA5	DAI_SDO	TX_EN1	FSMC_PCAD23	-
P4	MFIO48	SPORT_DTSEC1	TS_DATA4	DAI_SDI	AS_GPIO16	FSMC_WTn	-
R1	MFIO49	SPORT_DTSEC0	TS_DATA3	DAI_LRCLK	AS_GPIO17	FSMC_CLK	-
P3	MFIO50	SPORT_DRPRI	TS_DATA2	DAI_SCLK	AS_GPIO18	FSMC_Lbar	-
T2	MFIO51	SPORT_RFS	TS_DATA1	DAI_MCLK	AS_GPIO19	FSMC_PCSel0	-
T4	MFIO52	SPORT_DTPRI	TS_DATA0	AS_GPIO20	-	FSMC_PCSel1	-
P1	MFIO53	SPORT_TFS	TS_DVALID	AS_GPIO21	-	FSMC_PCSel2	-
P2	MFIO54	SPORTnCLK	TS_SYNC	AS_GPIO22	-	FSMC_PCSel3	-
N1	MFIO55	SPORT_TSCLK	TS_CLK	AS_GPIO23	-	FSMC_PCWaitn	-
N4	MFIO56	-	-	-	eth_phy_int	-	-
N2	MFIO57	-	-	-	eth_clk	-	-
N3	MFIO58	CLCD_PWR	-	-	MII_TXER	-	-
M2	MFIO59	CLCD_LE	-	-	MII_TXEN	-	-
M3	MFIO60	CLCD_LP	-	-	MII_TXD_3	-	-
L2	MFIO61	CLCD_FP	-	-	MII_TXD_2	-	-
L3	MFIO62	CLCD_CP	-	-	MII_TXD_1	-	-
L1	MFIO63	CLCD_AC	-	-	MII_TXD_0	-	-
L4	MFIO64	CLCD_D0	-	-	MII_TXCLK	-	-
K1	MFIO65	CLCD_D1	-	-	MII_RXER	-	-
K3	MFIO66	CLCD_D2	-	-	MII_RXDV	-	-
K2	MFIO67	CLCD_D3	-	-	MII_RXD_3	-	-



Table 16. MFIO pin descriptions (continued)

Ball no.	Signal name	Muxing selection					
		0	1	2	3	4	5
K4	MFIO68	CLCD_D4	-	-	MII_RXD_2	-	-
J1	MFIO69	CLCD_D5	-	-	MII_RXD_1	-	-
J3	MFIO70	CLCD_D6	-	-	MII_RXD_0	-	-
H1	MFIO71	CLCD_D7	-	-	MII_RXCLK	-	-
J4	MFIO72	CLCD_D8	AS_GPIO16	-	MII_MDIO	-	-
G1	MFIO73	CLCD_D9	AS_GPIO17	-	MII_MDC	-	-
J2	MFIO74	CLCD_D10	AS_GPIO18	-	MII_CRD	-	-
G2	MFIO75	CLCD_D11	AS_GPIO19	-	MII_COL	-	-
G3	MFIO76	CLCD_D12	AS_GPIO20	-	CAN1_RX	-	-
F3	MFIO77	CLCD_D13	AS_GPIO21	-	CAN1_TX	-	-
H2	MFIO78	CLCD_D14	AS_GPIO22	-	CAN2_RX	-	-
F1	MFIO79	CLCD_D15	AS_GPIO23	-	CAN2_TX	-	-
H4	MFIO80	CLCD_D16	-	UART1_CTS	-	-	-
F2	MFIO81	-	CLCD_D17	-	UART1_RTS	-	-
H3	MFIO82	I2C_SCL	CLCD_D18	-	UART1_RXD	-	-
E1	MFIO83	I2C_SDA	CLCD_D19	-	UART1_TXD	-	-
D3	MFIO84	SPI_SSP_SS	CLCD_D20	-	UART2_CTS	-	-
E2	MFIO85	SPI_SSP_SCLK	CLCD_D21	-	UART2_RTS	-	-
E3	MFIO86	SPI_SSP_MISO	CLCD_D22	-	UART2_RXD	-	-
D2	MFIO87	SPI_SSP_MOSI	CLCD_D23	-	UART2_TXD	-	-
AA10	MFIO88	CAN1_RX	ETM_PIPESTATB_2	-	-	-	-
Y10	MFIO89	CAN1_TX	ETM_PIPESTATB_1	-	-	-	-
AA11	MFIO90	CAN2_RX	ETM_PIPESTATB_0	-	-	-	-

**Table 16. MFIO pin descriptions (continued)**

Ball no.	Signal name	Muxing selection					
		0	1	2	3	4	5
Y11	MFIO91	CAN2_TX	ETM_TRACE_SYNCB	-	-	-	-
Y9	MFIO92	FSMC_PCIntRq_4	ETM_PIPESTATA_2	-	-	-	-
Y12	MFIO93	FSMC_PCIntRq_3	ETM_PIPESTATA_1	-	-	-	-
AA12	MFIO94	FSMC_PCIntRq_2	ETM_PIPESTATA_0	-	-	-	-
AB12	MFIO95	FSMC_PCIntRq_1	ETM_TRACE_SYNCA	-	-	-	-
AA13	MFIO96	GPT1_CPTR2	ETM_TRACEPKTB_3	-	-	-	-
AC12	MFIO97	GPT1_CPTR1	ETM_TRACEPKTB_2	-	-	-	-
AB11	MFIO98	GPT1_CLK2	ETM_TRACEPKTB_1	-	-	-	-
AB10	MFIO99	GPT1_CLK1	ETM_TRACEPKTB_0	-	-	-	-
AC11	MFIO100	GPT2_CPTR2	ETM_TRACEPKTA_3	-	-	-	-
Y8	MFIO101	GPT2_CPTR1	ETM_TRACEPKTA_2	-	-	-	-
AC10	MFIO102	GPT2_CLK2	ETM_TRACEPKTA_1	-	-	-	-
AC9	MFIO103	GPT2_CLK1	ETM_TRACEPKTA_0	-	-	-	-

### 4.3 Required external components

- COMP\_1V8\_ANAREXT: place an external 121 K $\Omega$  1% resistor between the ball B6 and ball C6
- USB\_TXRTUNE: connect an external 43.2  $\Omega$  1% pull-down resistor to the ball AB14
- COMP\_3V3\_ANAREXT: place an external 121 K $\Omega$  1% resistor between the ball A21 and ball A22
- PCIe\_REFRES: place an external 487  $\Omega$  1% resistor between the ball R20 and ball M21 (if using PCIe interface)
- DAC\_REXT: place an external 7.87 K $\Omega$  1% resistor between the ball V22 and ball U22
- DAC\_IDAC, DAC\_IDACB: place an external 1% accuracy load resistor between the ball V23 and ball U23 to ground.

## 5 Memory map

The memory map is shown in [Table 17](#).

**Table 17. Memory map description**

Start Address	End Address	Peripheral	Description
0x00000000	0x3FFFFFFF	External SDRAM	DDR2
0x40000000	0xBFFFFFFF	PCIe data	-
0xC0000000	0xC07FFFFFFF	S-ATA	-
0xC0800000	0xCFFFFFFF	-	Reserved
0xD0000000	0xD007FFFF	UART1	-
0xD0080000	0xD00FFFFFFF	UART2	-
0xD0100000	0xD017FFFF	SPI	-
0xD0180000	0xD01FFFFFFF	I <sup>2</sup> C	-
0xD0200000	0xD027FFFF	AES	-
0xD0280000	0xD02FFFFFFF	CAN1	-
0xD0300000	0xD03FFFFFFF	CAN2	-
0xD0400000	0xD07FFFFFFF	-	Reserved
0xD0800000	0xD0FFFFFFF	JPGC	-
0xD1000000	0xD17FFFFFFF	FirDA	-
0xD2800000	0xD2FFFFFFF	8 K SRAM	-
0xD3000000	0xD37FFFFFFF	FSMC controller	-
0xD3800000	0xD3FFFFFFF	FSMC - NAND memory	-
0xD4000000	0xD7FFFFFFF	FSMC - SRAM memory	-
0xD8000000	0xD807FFFF	PGC_IR	-
0xD8080000	0xD80FFFFFFF	DAI_I2S	-
0xD8100000	0xD817FFFF	AS_GPIO base address	-
0xD8180000	0xD87FFFFFFF	-	Reserved
0xD8800000	0xD8FFFFFFF	PLC modem	-
0xD9000000	0xD97FFFFFFF	TS	-
0xD9800000	0xD9FFFFFFF	SPORT	-
0xDA000000	0xDA7FFFFFFF	DES_TDES	-
0xDA800000	0xDAFFFFFFF	C3	-
0xDB000000	0xE07FFFFFFF	-	Reserved
0xE0800000	0xE0FFFFFFF	ETH	Ethernet MII - MAC
0xE1000000	0xE10FFFFFFF	USB 2.0 device controller	FIFO
0xE1100000	0xE11FFFFFFF	USB 2.0 device controller	Configuration registers

Table 17. Memory map description (continued)

Start Address	End Address	Peripheral	Description
0xE1200000	0xE12FFFFFFF	USB 2.0 device controller	Configuration plug detect
0xE1300000	0xE17FFFFFFF	-	Reserved
0xE1800000	0xE18FFFFFFF	USB 2.0 host controller	EHCI
0xE1900000	0xE19FFFFFFF	USB 2.0 host controller	OHCI
0xE1A00000	0xEFFFFFFF	-	Reserved
0xF0000000	0xF00FFFFFFF	GPT0	Timer 0 or CPU timer
0xF0100000	0xF0FFFFFFF	-	Reserved
0xF1000000	0xF107FFFF	PCIe DBI port	-
0xF1080000	0xF10FFFFFFF	PCIe MiPHY UPORT	-
0xF1100000	0xF11FFFFFFF	VIC	Vector interrupt controller
0xF1200000	0xF7FFFFFFF	-	Reserved
0xF8000000	0xFBFFFFFFF	SMI	Memory
0xFC000000	0xFC1FFFFFFF	SMI	Configuration registers
0xFC200000	0xFC3FFFFFFF	CLCD	-
0xFC400000	0xFC5FFFFFFF	DMAC	-
0xFC600000	0xFC7FFFFFFF	External SDRAM CFG	Configuration registers
0xFC800000	0xFC87FFFF	GPT1	Timer 1
0xFC880000	0xFC8FFFFFFF	WDG	Watchdog
0xFC900000	0xFC97FFFF	RTC	-
0xFC980000	0xFC99FFFF	GPIO1	-
0xFCA00000	0xFCA7FFFF	SYS_CTRL	System controller
0xFCA80000	0xFCAFFFFFFF	MISC	Miscellaneous registers
0xFCB00000	0xFCB7FFFF	GPT2	Timer 2
0xFCB80000	0xFCBFFFFFFF	GPIO2	-
0xFCC00000	0xFEFFFFFFF	-	Reserved
0xFF000000	0xFF00FFFF	48K_Boot_ROM	-
0xFF00C000	0xFFFFFFFF	-	Reserved

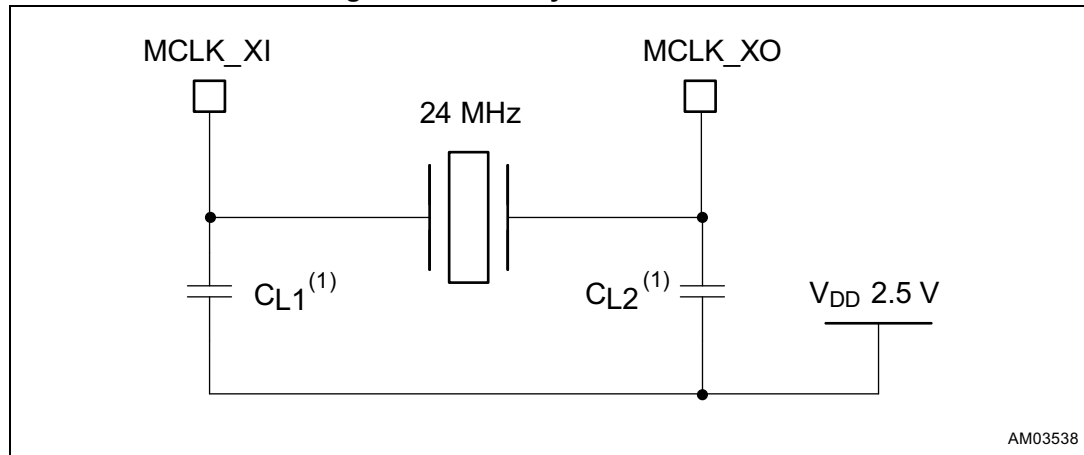
## 6 Clocking parameters

This section details clock related electrical specifications.

### 6.1 Master clock (MCLK)

The external circuit for generating the clock from a crystal oscillator is shown in [Figure 4](#).

**Figure 4. MCLK crystal connections**



1.  $C_{L1}$  and  $C_{L2}$  are the load capacitors.

The value of the capacitors depends on the type of the selected crystal. To calculate the value of the load capacitance, use [Equation 1](#).

For this example, an Aker C2E-24.000-12-3030-X 24 MHz oscillator has been used.

Load capacitance  $C_L$ :

#### Equation 1

$$C_L = (C_{L1} \times C_{L2} / C_{L1} + C_{L2}) + C_S$$

Where  $C_{L1}$  and  $C_{L2}$  are the load capacitors and  $C_S$  is the circuit's stray capacitance.

In our application this implies:

#### Equation 2

$$C_{L1} = C_{L2} = C_{ext}$$

#### Equation 3

$$C_{ext} = (C_L - C_S) \times 2$$

#### Example

For the Aker<sup>®</sup> C2E-24.000-12-3030-X crystal:

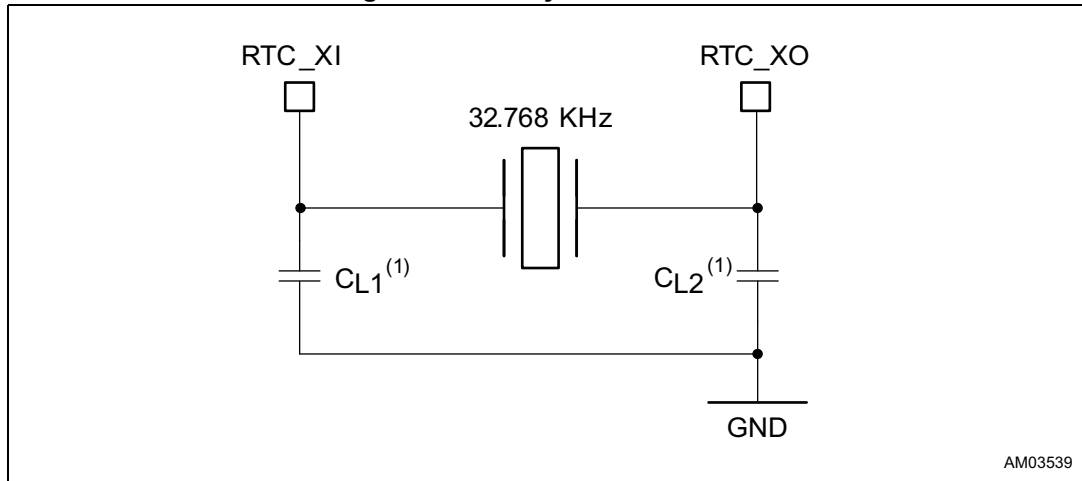
$$C_L = 12 \text{ PF}; \text{ with } C_S = 3 \text{ PF}, C_{ext} = C_{L1} = C_{L2} = 18 \text{ PF}.$$

*Note:* The ESR of the used quartz must be  $< 50 \Omega$ .

## 6.2 Real-time clock (RTC)

The external circuit for generating the real-time clock from a crystal oscillator is shown in [Figure 5](#).

**Figure 5. RTC crystal connection**



1.  $C_{L1}$  and  $C_{L2}$  are the load capacitors.

The value of the capacitors depends on the type of the selected crystal. For example, using a FOX Electronics<sup>®</sup>, P/N NC26LF-327 32.768 KHz oscillator, the value of the capacitors is 15 pF. The oscillator may not start if a crystal (FOX P/N FX325BS) is used.

If the shunt capacitance ( $C_o$ ) of the crystal is  $\sim 7.0$  pF, then the maximum ESR of the crystal must be less than 50  $\Omega$ .

## 6.3 PCIe/SATA clock

For SATA operation, the PCIE\_XTAL1/PCIE\_XTAL2 clock inputs can be implemented by a 30 MHz crystal oscillator as shown in [Table 18](#).

For PCIe operation, a suitable clock driver such as IDT IDT\_9FG104 can be used.

**Table 18. EXPI clock characteristics**

Symbol	Parameter	Min.	Typical	Max.	Unit
$f_{osc}$	PCIE_XTAL1/PCIE_XTAL2 clock input frequency for SATA configuration	-	30	-	MHz
	PCIE_XTAL1/PCIE_XTAL2 clock input frequency for PCIe configuration	-	100	-	

## 7 Electrical characteristics

This section provides electrical specifications for the SStreamPlug ST2100 device.

### 7.1 Absolute maximum ratings

This product contains devices to protect the inputs against damage due to high/low static voltages. However it is advisable to take normal precaution to avoid application of any voltage higher/lower than the specified maximum/minimum rated voltages.

The absolute maximum ratings shown in [Table 19](#) are the maximum stress that can be applied to a device without causing permanent damage. However, extended exposure to minimum/maximum ratings may affect long term device reliability.

**Table 19. Absolute maximum rating**

Symbol	Parameter	Min.	Max.	Unit
V <sub>DD</sub> 1.2	Supply voltage for the core	-0.3	1.32	V
V <sub>DD</sub> 3.3	Supply voltage for the I/Os	-0.3	3.63	V
V <sub>DD</sub> 2.5	Supply voltage for the DDR/AFE	-0.3	2.75	V
V <sub>DD</sub> 1.5	Supply voltage for the real-time clock	-0.3	2.75	V
T <sub>STG</sub>	Storage temperature	-55	150	°C
T <sub>J</sub>	Junction temperature	-40	125	°C

### 7.2 Power consumption

In [Table 20](#) and [Table 21](#) power consumption data are based on bench measurements with devices using the Linux OS, the CPU and DDR2 running at 333 MHz and all on-chip peripherals and internal modules enabled while the SStreamPlug ST2100 is transferring a file from the USB Flash memory to the powerline.

**Table 20. Power consumption**

Symbol	Parameter	Typical	Unit
PD (core supply)	Power consumption of 1.2 V supply voltage for the core	460	mW
PD (IO supply)	Power consumption of 3.3 V supply voltage for the I/Os	270	mW
PD (AFE supply)	Power consumption of 2.5 V supply voltage	260	mW
PD (DDR supply)	Power consumption of 1.8 V supply voltage for the DDR interface	170	mW
PD (RTC supply)	Power consumption of 1.5 V supply voltage for the RTC	9	μW



**Table 21. Power consumption using 2.5 V internal LDO**

Symbol	Parameter	Typical	Unit
$P_D$ (core supply)	Power consumption of 1.2 V supply voltage for the core	460	mW
$P_D$ (IO supply)	Power consumption of 3.3 V supply voltage for the I/Os	630	mW
$P_D$ (DDR supply)	Power consumption of 1.8 V supply voltage for the DDR interface	170	mW
$P_D$ (RTC supply)	Power consumption of 1.5 V supply voltage for the RTC	9	$\mu$ W

### 7.3 DC electrical characteristics

The recommended operating conditions are listed in [Table 22](#) and [Table 23](#).

**Table 22. Recommended operating conditions**

Symbol	Parameter	Min.	Typical	Max.	Unit
$V_{DD1.2}$	Supply voltage for the core	1.08	1.2	1.32	V
$V_{DD3.3}$	Supply voltage for the I/Os	2.97	3.3	3.63	V
$V_{DD2.5}$	Supply voltage for the analog peripherals	2.25	2.5	2.75	V
$V_{DD1.8/2.5}$	Supply voltage for the DDR	-10%	2.5 V / 1.8 V	+10%	V
$V_{DD1.5}$	Supply voltage for the RTC	1.3	1.5	2.0	V
$V_{DD3.3 REG}$	Supply voltage for 2.5 V linear regulator	2,97	3.3	3.63	V

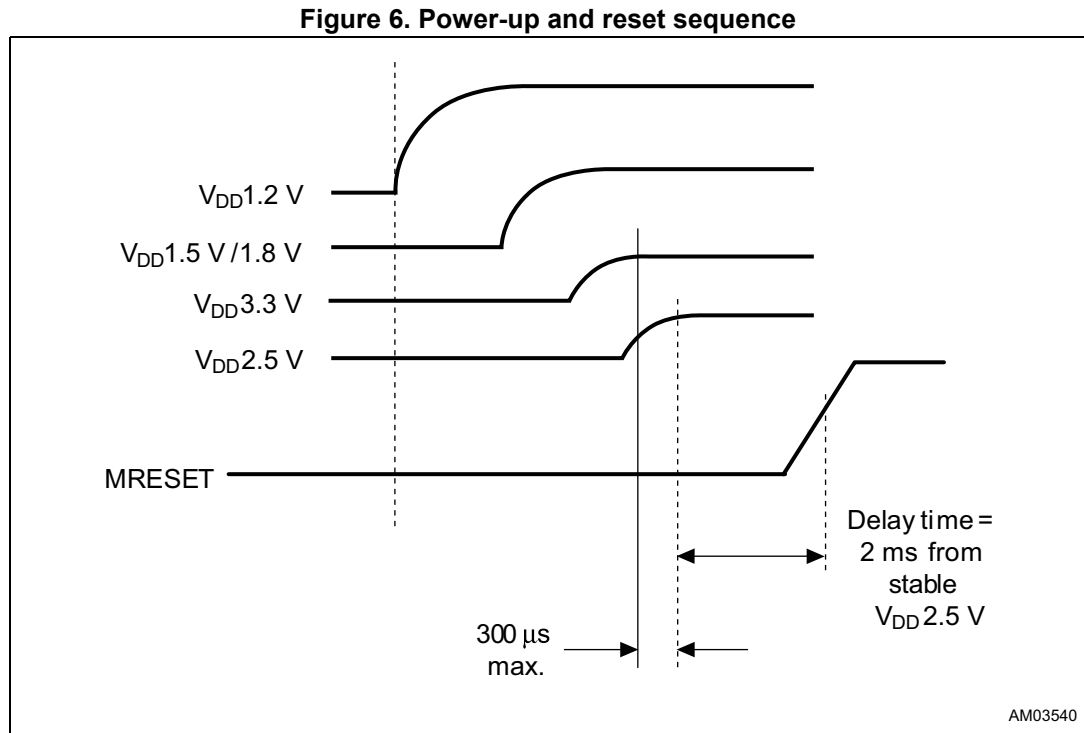
**Table 23. Thermal recommended ratings**

Symbol	Parameter	Min.	Max.	Unit
$T_{STG}$	Storage temperature range	-55	150	$^{\circ}$ C
$T_J$	Junction temperature	-40	125	-
$T_a$	Ambient temperature	-40	85	-

Thermal simulations should be done to verify if additional cooling is required. These simulations should take into account power consumption, PCB dissipation, air flow and/or heatsinks. The SStreamPlug device can perform correctly above the specified ambient temperature range if the maximum junction temperature remains below 125  $^{\circ}$ C.

### 7.4 Power-up and reset sequence

The master reset (MRESET) must be released after the  $V_{DD2.5}$  power supply is stable for a time interval of 2 ms, which is the start-up time of the main oscillator, as illustrated in [Figure 6](#).



### 7.5 Internal 2.5 V linear regulator

The internal linear regulator specified in [Table 24](#) provides a regulated 2.5 V power supply for on-chip AFE, OSCI, PLL, USB PHY, PCIe PHY and SYNTH functional blocks.

The 2.5 V regulator cannot be used to supply external devices.

**Table 24. Internal 2.5 V voltage regulator specifications**

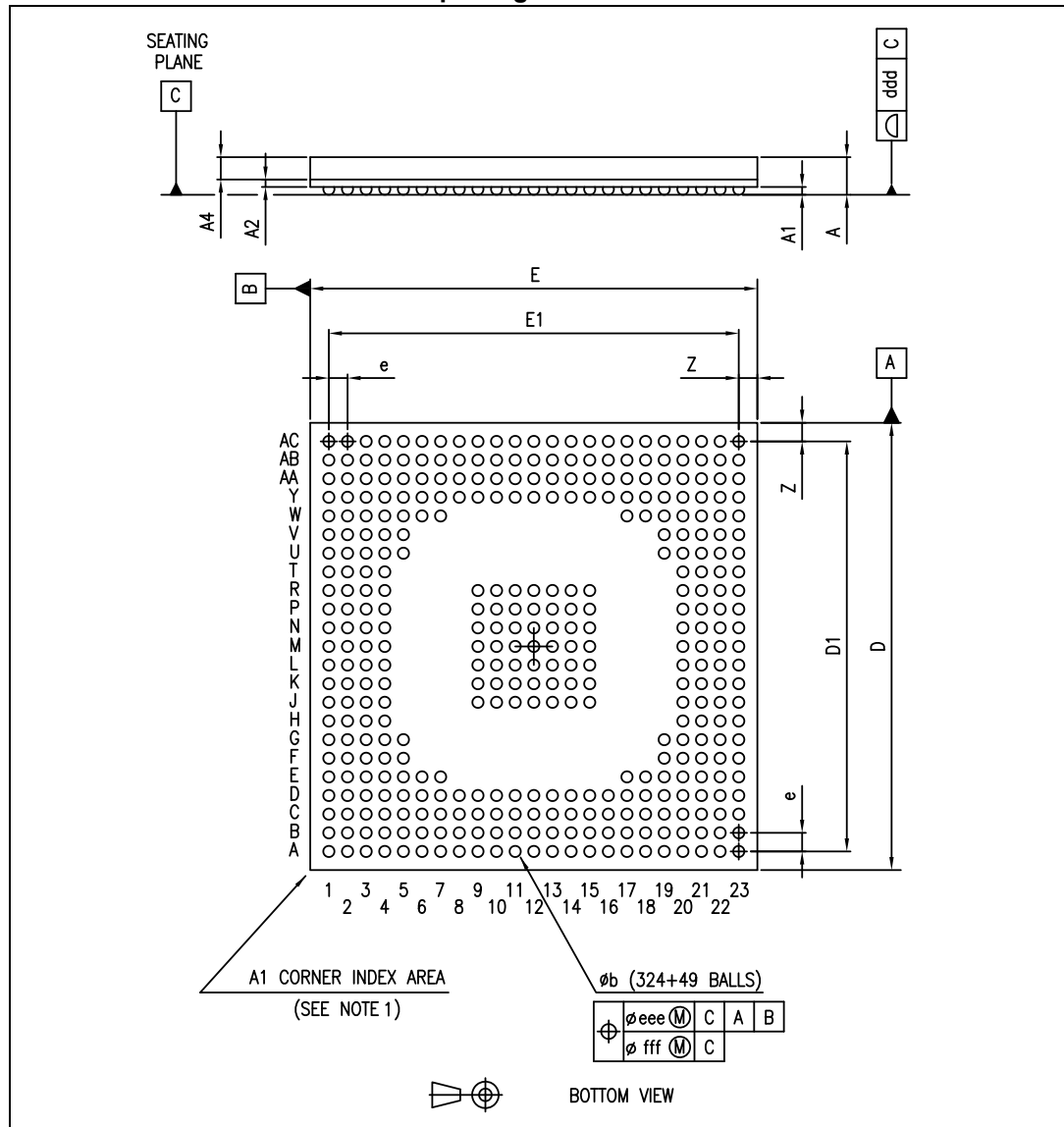
Symbol	Parameter	Min.	Typical	Max.	Unit
$V_{DD3.3\text{ REG}}$	Supply voltage for 2.5 V linear regulator	2.97	3.3	3.36	V
$V_{DD2.5\text{ REG}}$	Output voltage of 2.5 V linear regulator	2.25	2.5	2.75	V
$I_{LOAD2.5\text{ REG}}$	Output current of 2.5 V linear regulator	-	-	150	mA

## 8 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK is an ST trademark.

### 8.1 TFBGA 12 x 12 x 1.2 mm package information

Figure 7. TFBGA 12 x 12 x 1.2 mm, 324 + 49 balls, 4R23 x 23, pitch 0.5 mm, ball 0.3 mm package outline



1. The terminal A1 corner must be identified on the top surface by using a corner chamfer, ink or metalized markings, or other feature of package body or integral heatslug. A distinguishing feature is allowable on the bottom surface of the package to identify the terminal A1 corner. Exact shape of each corner is optional.

Table 25 lists the mechanical data for the package shown in Figure 7.

**Table 25. TFBGA 12 x 12 x 1.2 mm, 324 + 49 balls, 4R23 x 23, pitch 0.5 mm, ball 0.3 mm package mechanical data**

Symbol	Dimensions (mm)			Note
	Min.	Typical	Max.	
A	-	-	1.20	(1)
A1	0.15	-	-	-
A2	-	0.20	-	-
A4	-	0.585	-	-
b	0.25	0.30	0.35	(2)
D	11.85	12.00	12.15	-
D1	-	11.00	-	-
E	11.85	12.00	12.15	-
E1	-	11.00	-	-
e	-	0.50	-	-
Z	-	0.50	-	-
ddd	-	-	0.08	-
eee	-	-	0.15	(3)
fff	-	-	0.05	(4)

- The total profile height (dim. A) is measured from the seating plane to the top of the component. The maximum total package height is calculated by the following methodology:  $A1\text{ typ.} + A2\text{ typ.} + A3\text{ typ.} + \sqrt{A1^2 + A2^2 + A3^2}$  tolerance values.  
Thin profile:  $1.00 < A < 1.20$  mm / fine pitch:  $e < 1.00$  mm pitch.
- The typical ball diameter before mounting is 0.30 mm.
- The tolerance of position that controls the location of the pattern of balls with respect to datums A and B. For each ball there is a cylindrical tolerance zone "eee" perpendicular to datum "C" and located on true position with respect to datums "A" and "B" as defined by "e". The axis perpendicular to datum "C" of each ball must lie within this tolerance zone.
- The tolerance of position that controls the location of the balls within the matrix with respect to each other. For each ball there is a cylindrical tolerance zone "fff" perpendicular to datum "C" and located on true position as defined by "e". The axis perpendicular to datum "C" of each ball must lie within this tolerance zone. Each tolerance zone "fff" in the array is contained entirely in the respective zone "eee" above. The axis of each ball must lie simultaneously in both tolerance zones.

The TFBGA ("Thin profile Fine Pitch Ball Grid Array") package uses a grid of solder balls as its connectors. The TFBGA package is noted for its compact size, high lead count and low inductance, which allows lower voltages to be used.

Table 26 lists thermal characteristics for the TFBGA package.

**Table 26. TFBGA package thermal characteristics**

Symbol	Parameter	Value	Unit
$\Theta_{JA}^{(1)}$	Thermal resistance junction to ambient	33	°C/W

- Measured on a JESD51 2S2P test board.

## 9 Revision history

Table 27. Document revision history

Date	Revision	Changes
23-May-2014	1	Initial release.
06-Feb-2018	2	Updated <a href="#">Section : Applications on page 1</a> . Minor modifications throughout document.

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